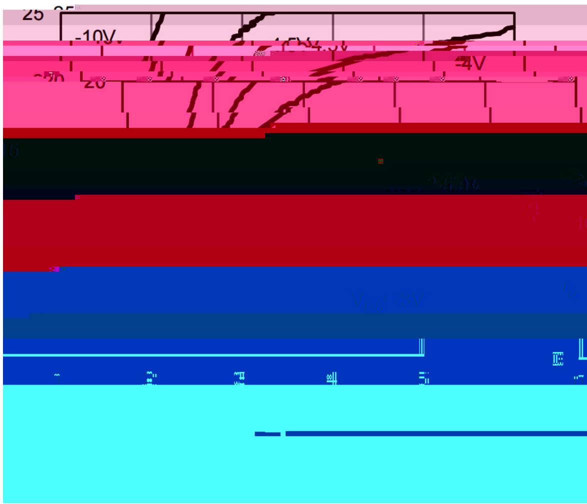
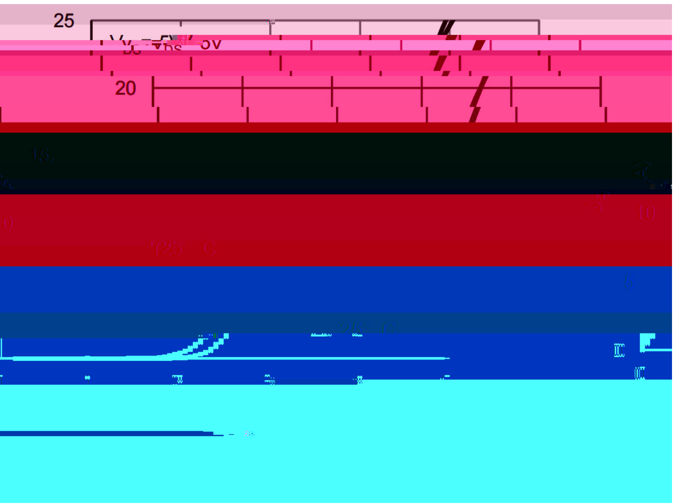
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_g(10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-4.1A		8.5		nC
Total Gate Charge	Q_g(4.5V)			4.5		
Gate Source Charge	Q_{gs}			1.5		
Gate Drain Charge	Q_{gd}			2.0		

Turn–On Delay Time $t_{d(on)}$

V_{GSg}

/ Electrical Characteristic Curve





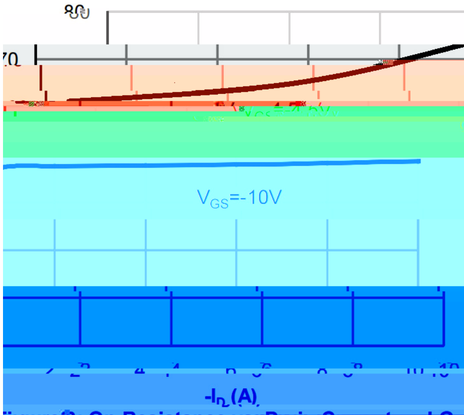


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

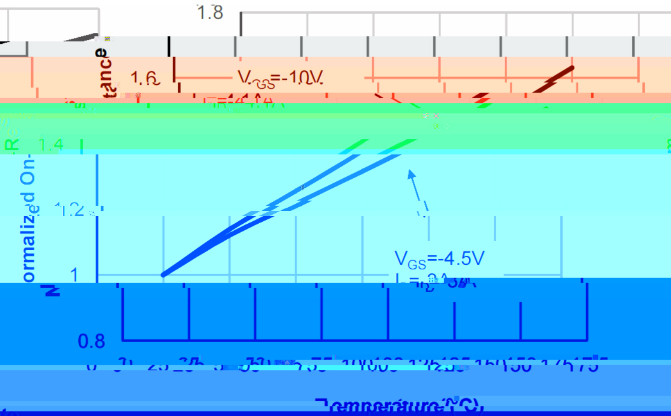
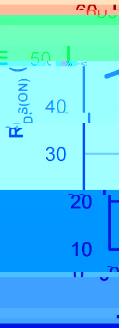
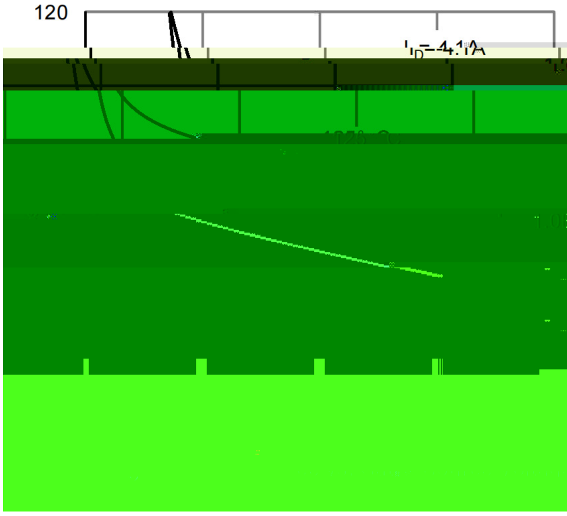
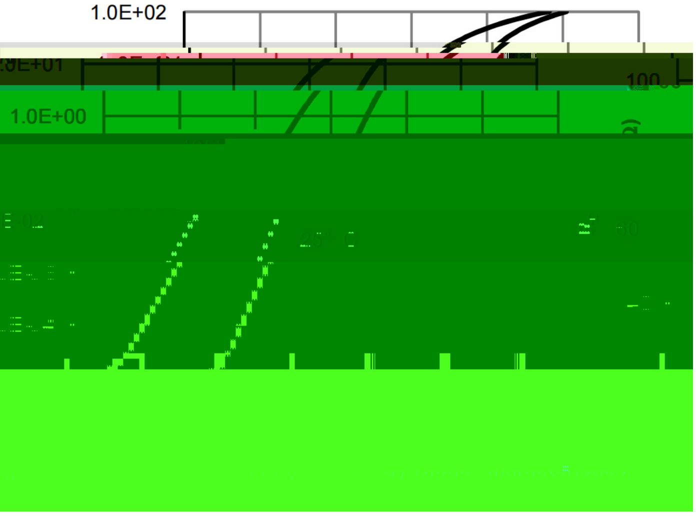


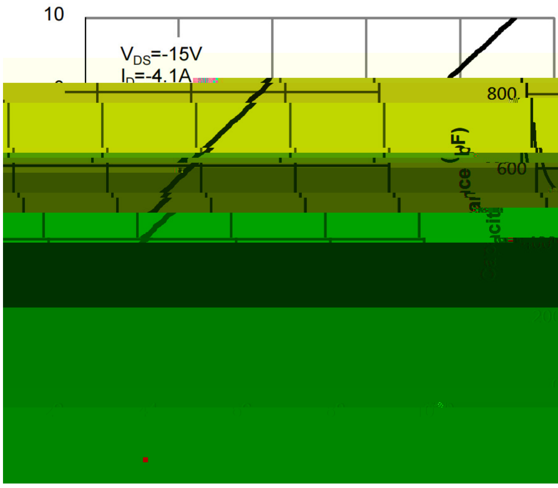
Figure 4: On-Resistance vs. Junction Temperature

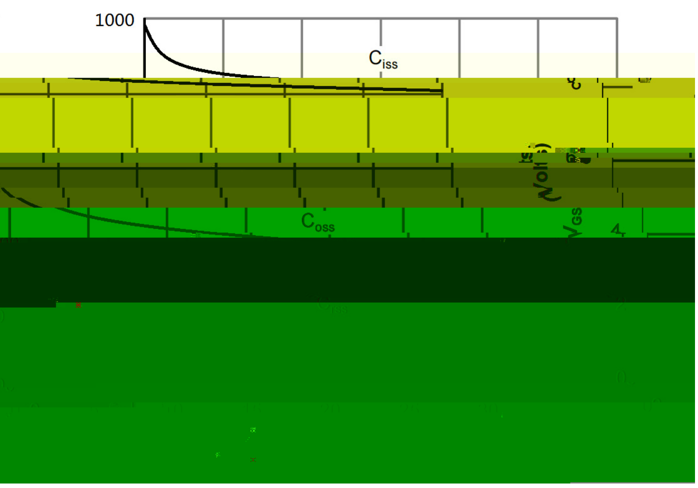


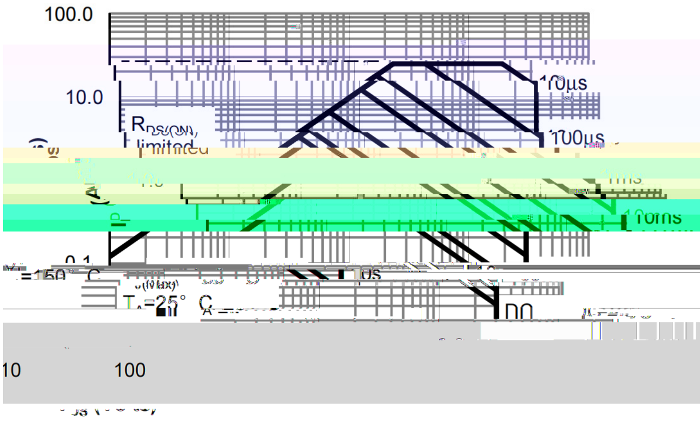




/ Electrical Characteristic Curve







ximum Forward Biased Safe Operating Area

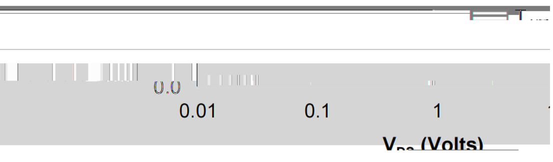
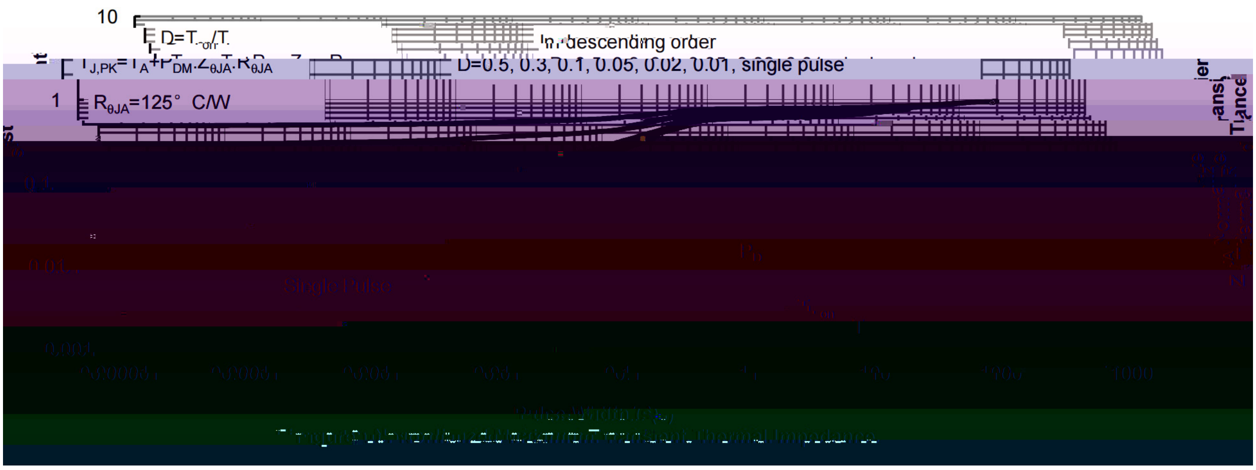
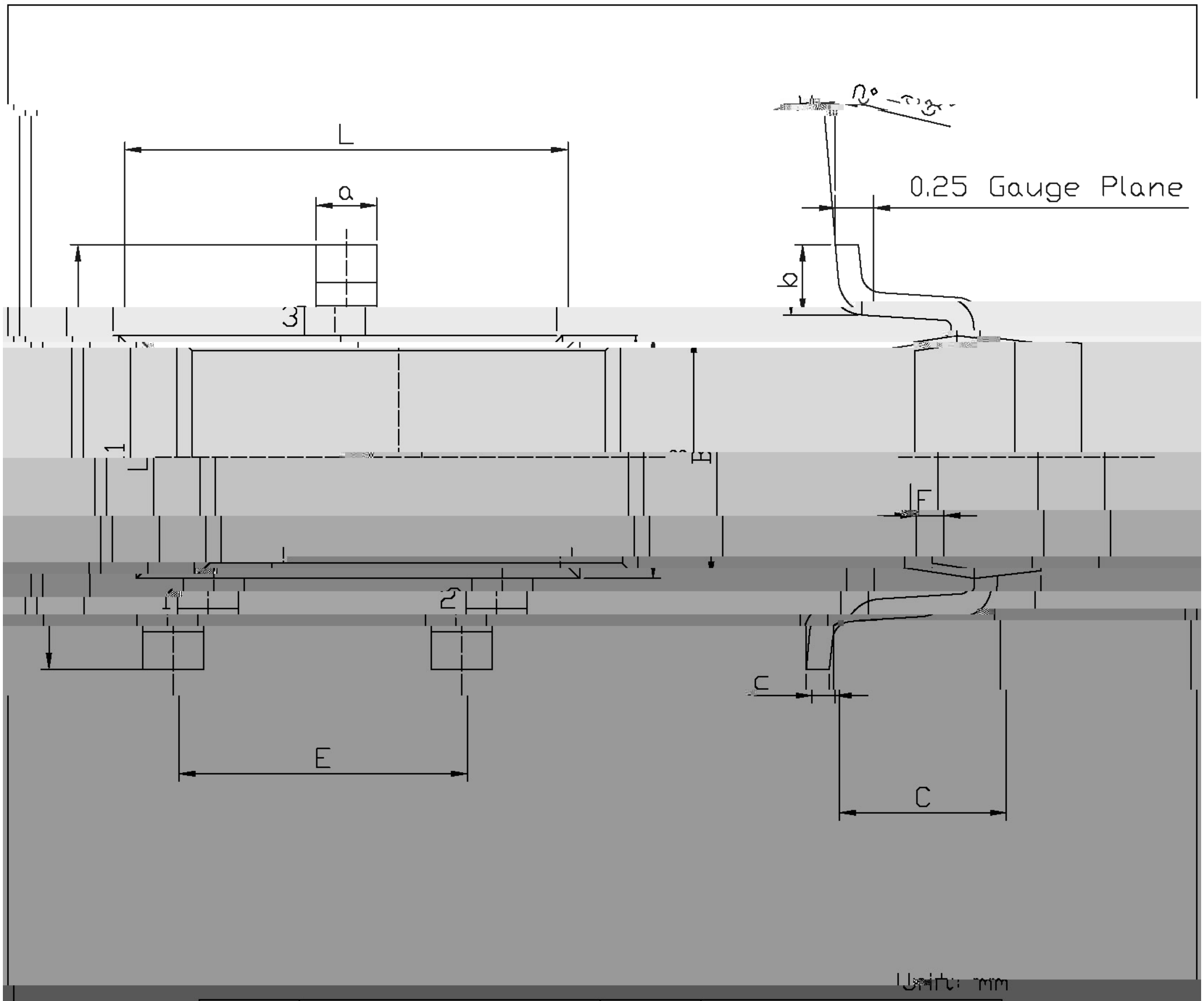


Figure 9: Ma



/ Package Dimensions



(   ) /   Temperature Profile for IR Reflow Soldering(Pb-Free)

	Note:
1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/   Resistance to Soldering Heat Test Conditions

260 5   10 1 sec.   Temp.:260±5   Time:10±1 sec

/   Packaging SPEC.

/ REEL